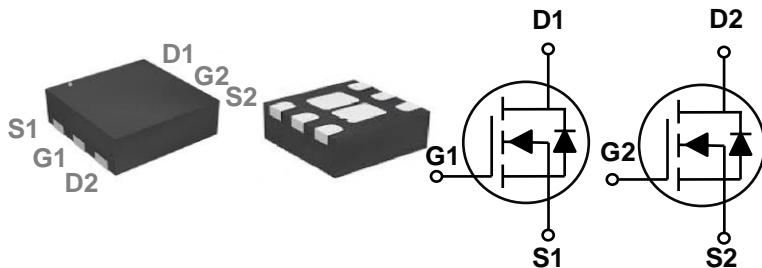


20V Dual N-Channel MOSFETs

General Description

These dual N Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

DFN2X2 Dual 2EP Pin Configuration



BVDSS	RDS(on)	ID
20V	40mΩ	5.2A

Features

- Fast switching
- Green Device Available
- Suit for 1.8V Gate Drive Applications

Applications

- Notebook
- Load Switch
- Networking
- Hand-held Instruments

Absolute Maximum Ratings ($T_c = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	20	V
V_{GS}	Gate-Source Voltage	± 10	V
I_D	Drain Current – Continuous ($T_c=25^\circ\text{C}$)	5.2	A
	Drain Current – Continuous ($T_c=100^\circ\text{C}$)	3.3	A
I_{DM}	Drain Current – Pulsed ¹	20.8	A
P_D	Power Dissipation ($T_c=25^\circ\text{C}$)	1.78	W
	Power Dissipation – Derate above 25°C	0.02	W/ $^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction to Ambient	---	100	$^\circ\text{C}/\text{W}$



FTK2216DFN22NN

20V Dual N-Channel MOSFETs

Electrical Characteristics ($T_J=25^\circ\text{C}$, unless otherwise noted)

Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	20	---	---	V
$\Delta \text{BV}_{\text{DSS}}/\Delta T_J$	BV_{DSS} Temperature Coefficient	Reference to 25°C , $I_D=1\text{mA}$	---	0.02	---	$\text{V}/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=25^\circ\text{C}$	---	---	1	μA
		$V_{\text{DS}}=16\text{V}$, $V_{\text{GS}}=0\text{V}$, $T_J=125^\circ\text{C}$	---	---	10	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 10\text{V}$, $V_{\text{DS}}=0\text{V}$	---	---	± 100	nA

On Characteristics

$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance	$V_{\text{GS}}=4.5\text{V}$, $I_D=3\text{A}$	---	30	40	$\text{m}\Omega$
		$V_{\text{GS}}=2.5\text{V}$, $I_D=2\text{A}$	---	42	55	$\text{m}\Omega$
		$V_{\text{GS}}=1.8\text{V}$, $I_D=1.5\text{A}$	---	55	80	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}$, $I_D=250\mu\text{A}$	0.3	0.6	1	V
$\Delta V_{\text{GS(th)}}$	$V_{\text{GS(th)}}$ Temperature Coefficient		---	-2	---	$\text{mV}/^\circ\text{C}$
g_{fs}	Forward Transconductance	$V_{\text{DS}}=10\text{V}$, $I_D=2\text{A}$	---	4.4	---	S

Dynamic and switching Characteristics

Q_g	Total Gate Charge ^{2, 3}	$V_{\text{DS}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $I_D=3\text{A}$	---	5.8	10	nC
Q_{gs}	Gate-Source Charge ^{2, 3}		---	0.6	1.5	
Q_{gd}	Gate-Drain Charge ^{2, 3}		---	1.5	3	
$T_{\text{d(on)}}$	Turn-On Delay Time ^{2, 3}	$V_{\text{DD}}=10\text{V}$, $V_{\text{GS}}=4.5\text{V}$, $R_G=25\Omega$ $I_D=1\text{A}$	---	2.9	6	ns
T_r	Rise Time ^{2, 3}		---	8.4	16	
$T_{\text{d(off)}}$	Turn-Off Delay Time ^{2, 3}		---	19.2	38	
T_f	Fall Time ^{2, 3}		---	5.6	12	
C_{iss}	Input Capacitance	$V_{\text{DS}}=15\text{V}$, $V_{\text{GS}}=0\text{V}$, $F=1\text{MHz}$	---	315	600	pF
C_{oss}	Output Capacitance		---	50	80	
C_{rss}	Reverse Transfer Capacitance		---	40	60	

Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_s	Continuous Source Current	$V_G=V_D=0\text{V}$, Force Current	---	---	3.8	A
I_{SM}	Pulsed Source Current		---	---	7.6	A
V_{SD}	Diode Forward Voltage	$V_{\text{GS}}=0\text{V}$, $I_s=1\text{A}$, $T_J=25^\circ\text{C}$	---	---	1	V

Note :

- Repetitive Rating : Pulsed width limited by maximum junction temperature.
- The data tested by pulsed, pulse width $\leq 300\text{us}$, duty cycle $\leq 2\%$.
- Essentially independent of operating temperature.

20V Dual N-Channel MOSFETs

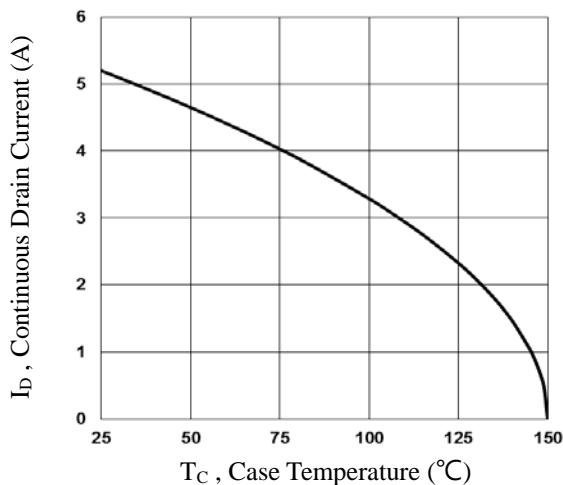


Fig.1 Continuous Drain Current vs. T_C

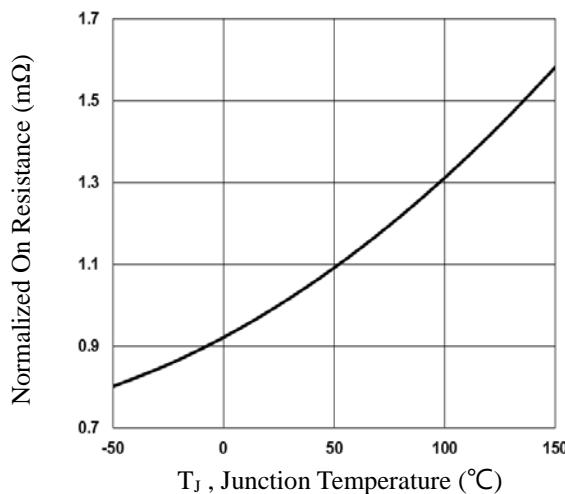


Fig.2 Normalized RDS(on) vs. T_J

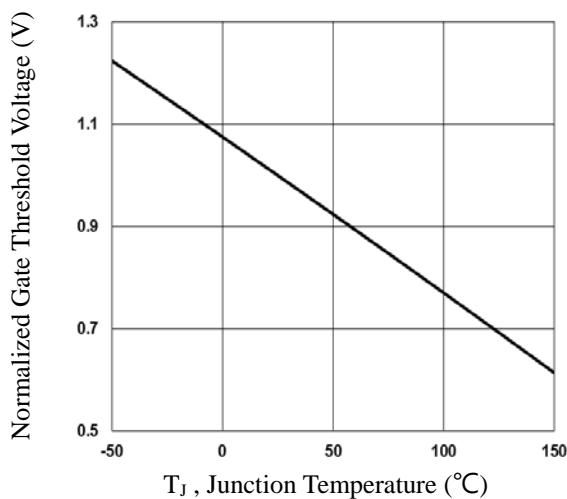


Fig.3 Normalized V_{th} vs. T_J

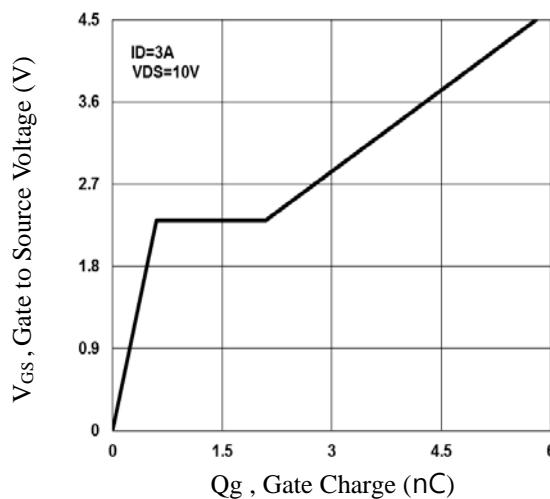


Fig.4 Gate Charge Waveform

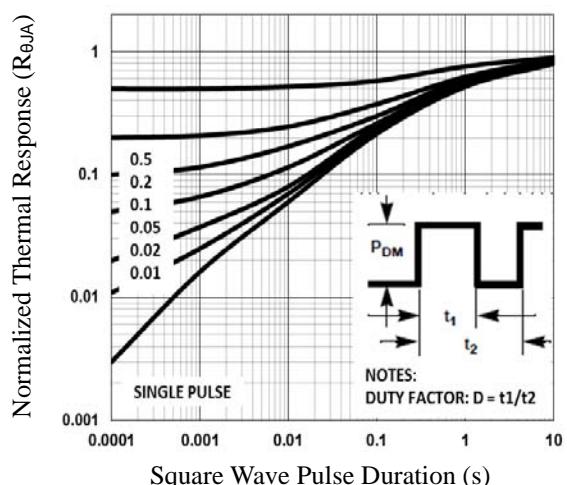


Fig.5 Normalized Transient Impedance

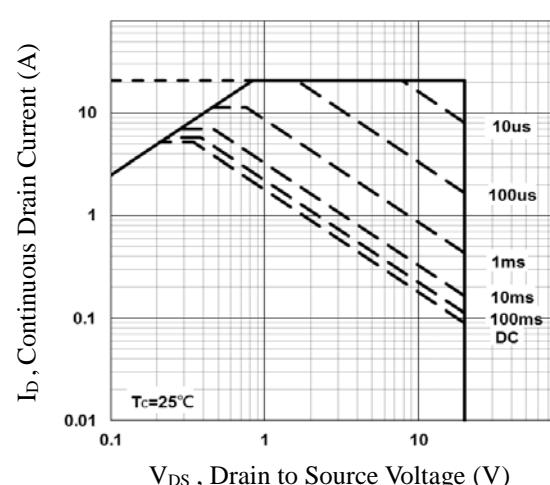


Fig.6 Maximum Safe Operation Area

20V Dual N-Channel MOSFETs

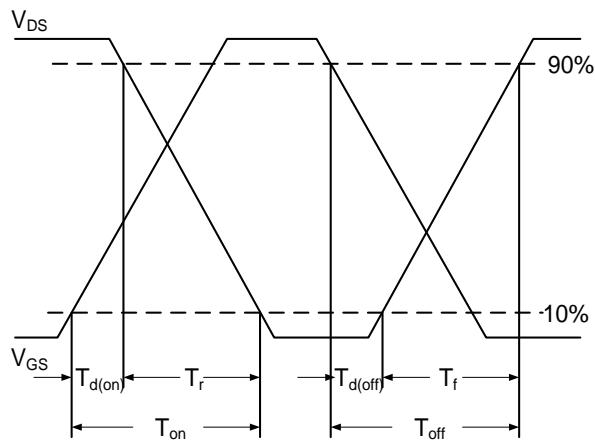


Fig.7 Switching Time Waveform

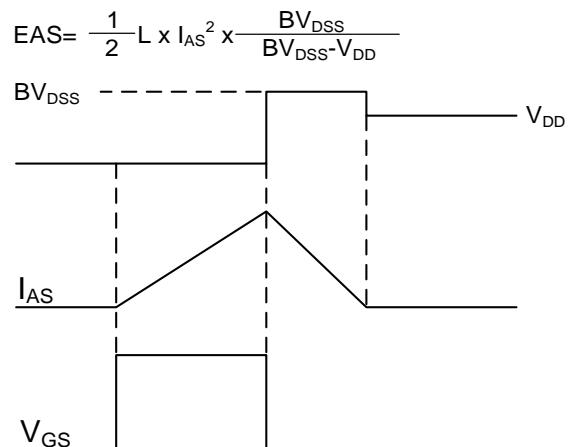
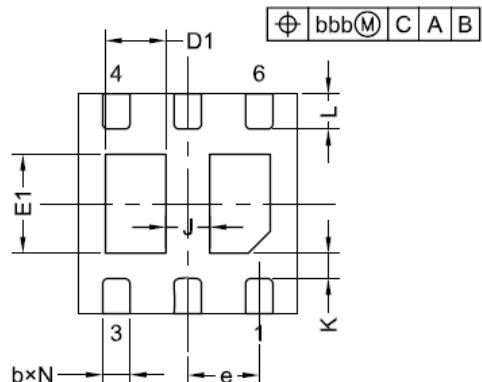


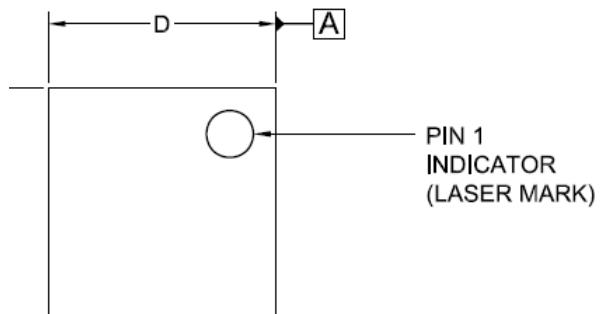
Fig.8 EAS Waveform

20V Dual N-Channel MOSFETs

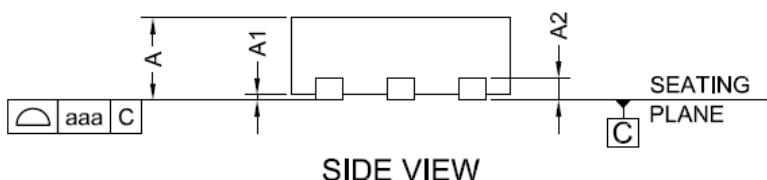
PPAK2X2 Dual 2EP PACKAGE INFORMATION



BOTTOM VIEW



TOP VIEW



SIDE VIEW

COMMON DIMENSIONS
(UNITS OF MEASURE=MILLIMETER)

SYMBOL	MIN	TYP	MAX
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2			0.203
b	0.20	0.25	0.30
D	1.95	2.00	2.05
D1	0.50	0.55	0.60
E	1.95	2.00	2.05
E1	0.85	0.90	0.95
e	0.65BSC		
L	0.27	0.32	0.37
J	0.40BSC		
K	0.20MIN		
N	6		
aaa	0.08		
bbb	0.10		